

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------------------------|---------------------|
| 1 | 1396 | wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:06 |
| 2 | 1056 | (wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:07 |
| 3 | 399 | ((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 12:51 |
| 4 | 207 | ((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap))) and (Wafer near silicon) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:03 |
| 5 | 35 | 5286671.URPN. | USPAT | 2004/04/29 13:57 |
| 6 | 0 | 438/464.ccls. and beol | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:05 |
| 7 | 1 | ((wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) and (@ad<20010601)) and (Wafer near (via or thru or through or hole or holes or vias or opening or open or gap))) and (beol or (back near line)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:04 |
| 8 | 8646 | ((@ad<20010601) and (beol or (back near line))) and (wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:04 |
| 9 | 3 | ((@ad<20010601) and (beol or (back near line))) and (wafer near ((thin or thinning or etch or etching or grind or grinding) and (holder or handle or temporary or support))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:05 |
| 10 | 2 | 438/464.ccls. and (back near line) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:06 |
| 11 | 46 | ((@ad<20010601) and (beol or (back near line))) and (wafer with (holder or handle or temporary or support)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:07 |
| 12 | 46 | ((@ad<20010601) and (beol or (back near line))) and (wafer with (holder or handle or temporary or support))) and (@ad<20010601) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/04/29 14:07 |